# Dual $\pm 25 \mathrm{~V}$ Above- and Below-the-Rails 4:1 Analog Multiplexer 

## General Description

The MAX14778 dual 4:1 analog multiplexer supports analog signals up to $\pm 25 \mathrm{~V}$ with a single 3.0 to 5.5 V supply. Each multiplexer has separate control inputs to allow independent switching, making the device ideal for multiplexing different communications signals with the same connector pins. Extended ESD protection of $\pm 6 \mathrm{kV}$ (Human Body Model) enable direct interfacing to cables and connectors.
The MAX14778 features a low $1.5 \Omega$ (max) on-resistance and $3 m \Omega$ (typ) flatness to maximize signal integrity over the entire common-mode voltage range. Each multiplexer can carry up to 300 mA of continuous current through the multiplexer in either direction.
The MAX14778 supports switching of full-speed USB 1.1 signals (12Mbps) and RS-485 data rates of up to 20Mbps.
The MAX14778 is available in a $20-\mathrm{pin}$ ( $5 \mathrm{~mm} \times 5 \mathrm{~mm}$ ) TQFN package and is specified over the $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ extended temperature range.

Applications
RS-485/RS-232/USB 1.1 Multiplexing
POS Peripherals
Handheld Industrial Devices
Communication Systems
Audio/Data Multiplexing
Connector Sharing
Gaming Machines

Features

## - $\pm 25 \mathrm{~V}$ Signal Range <br> - Single 3.0V to 5.5V Supply <br> - Two Independent Multiplexers <br> - $1.5 \Omega$ RON (max) <br> - 3ms Ron Flatness (typ) <br> - 300mA Maximum Current Through Multiplexer <br> - 78pF Input Capacitance <br> - 75MHz Large-Signal Bandwidth <br> - Break-Before-Make Operation <br> - Extended ESD Protection on A_ and B_Pins $\diamond \pm 6 k V$ Human Body Model (HBM)

## Ordering Information appears at end of data sheet.

For related parts and recommended products to use with this part, refer to www.maximintegrated.com/MAX14778.related.

Functional Diagram


## Dual $\pm 25 V$ Above- and Below-the-Rails 4:1 Analog Multiplexer

## ABSOLUTE MAXIMUM RATINGS

(All voltages referenced to GND.)


| Continuous Current Through Switch ......................... $\pm 500 \mathrm{~mA}$ |  |
| :---: | :---: |
| Continuous Power Dissipation ( $\mathrm{T}_{\mathrm{A}}=+70^{\circ} \mathrm{C}$ ) |  |
| TQFN (derate $33.3 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $+70^{\circ} \mathrm{C}$ )... | .2666.7mW |
| Operating Temperature Range | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ |
| Junction Temperature | $+150^{\circ} \mathrm{C}$ |
| Storage Temperature Range. | $-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$ |
| Lead Temperature (soldering, 10s) | $+300^{\circ} \mathrm{C}$ |
| Soldering Temperature (reflow) | $+260^{\circ} \mathrm{C}$ |

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## PACKAGE THERMAL CHARACTERISTICS (Note 1)

TQFN
Junction-to-Ambient Thermal Resistance ( $\theta_{\mathrm{JA}}$ ) $\ldots . . . . . .30^{\circ} \mathrm{C} / \mathrm{W}$
Junction-to-Case Thermal Resistance ( $\theta_{\mathrm{Jc}}$ ) ................. $2^{\circ} \mathrm{C} / \mathrm{W}$
Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

## ELECTRICAL CHARACTERISTICS

( $\mathrm{V}_{\mathrm{DD}}=3.0 \mathrm{~V}$ to $5.5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted. Typical values are at $\mathrm{V}_{\mathrm{DD}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$.) (Note 2)

| PARAMETER | SYMBOL | CONDITIONS |  | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| DC CHARACTERISTICS |  |  |  |  |  |  |  |
| Supply Voltage Range | $V_{\text {DD }}$ |  |  | 3.0 |  | 5.5 | V |
| Supply Current | ${ }^{\text {DD }}$ | $\mathrm{ENA}=\mathrm{ENB}=$ high | $\mathrm{V}_{\mathrm{DD}} \leq \mathrm{V}_{\text {DDTH }}$ |  | 4.27 | 10 | mA |
|  |  |  | $\mathrm{V}_{\mathrm{DD}}>\mathrm{V}_{\text {DDTH }}$ |  | 2.54 | 6 |  |
|  |  | $\mathrm{V}_{\mathrm{ENA}}=\mathrm{V}_{\mathrm{ENB}}=\mathrm{V}_{\mathrm{DD}} / 2$ | $\mathrm{V}_{\mathrm{DD}} \leq \mathrm{V}_{\text {DDTH }}$ |  | 4.31 | 10 |  |
|  |  |  | $\mathrm{V}_{\mathrm{DD}}>\mathrm{V}_{\text {DDTH }}$ |  | 2.59 | 6 |  |
| Charge-Pump Threshold | $\mathrm{V}_{\text {DDTH }}$ | (Note 3) |  | 4.64 |  |  | V |
| Analog Signal Range | $\mathrm{V}_{\text {IN }}$ | Figure 1, switch open or closed |  | -25 |  | +25 | V |
| Continuous Current Through Switch | ICOM |  |  | -300 |  | +300 | mA |
| On-Resistance | $\mathrm{R}_{\mathrm{ON}}$ | Figure 1, $\mathrm{I}_{\text {COM }}= \pm 300 \mathrm{~mA}, \mathrm{~V}_{\text {IN }}= \pm 25 \mathrm{~V}$ |  |  | 0.84 | 1.5 | $\Omega$ |
| On-Resistance Flatness | RFLAt(ON) | Figure $1,-25 \mathrm{~V} \leq \mathrm{V}_{\mathrm{IN}} \leq+25 \mathrm{~V}$, $I_{C O M}= \pm 300 \mathrm{~mA}$ |  |  | 3 |  | $\mathrm{m} \Omega$ |
| A_, B_Off-Leakage Current | $I_{\text {A(OFF), }}$ <br> B(OFF) | Figure 2, $\mathrm{V}_{\text {IN }}=25 \mathrm{~V}, \mathrm{~V}_{\text {OUT }}=0 \mathrm{~V}$ |  | -200 |  | +200 | nA |
| ACOM, BCOM <br> Off-Leakage Current | IACOM(OFF), IBCOM(OFF) | Figure 2, $\mathrm{V}_{\text {OUT }}=15 \mathrm{~V}, \mathrm{~V}_{\text {IN }}=0 \mathrm{~V}$ |  | -1 |  | +1 | $\mu \mathrm{A}$ |
| A_, B_On-Leakage Current | $\mathrm{I}_{\mathrm{A}(\mathrm{ON}),}$ $\left.{ }_{\mathrm{B}}^{\mathrm{B}} \mathrm{ON}\right)$ | Figure $2, \mathrm{~V}_{\mathrm{IN}}= \pm 25 \mathrm{~V}$, ACOM or BCOM is unconnected |  | -1 |  | +1 | $\mu \mathrm{A}$ |

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## ELECTRICAL CHARACTERISTICS (continued)

$\left(V_{D D}=3.0 \mathrm{~V}\right.$ to $5.5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted. Typical values are at $\mathrm{V}_{\mathrm{DD}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$.) (Note 2)

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| LOGIC INPUTS (ENA, ENB, SA_, SB_) |  |  |  |  |  |  |
| Input Logic-Low Voltage | $\mathrm{V}_{\text {IL }}$ | $\mathrm{V}_{\mathrm{DD}}=5.5 \mathrm{~V}$ |  |  | 0.8 | V |
|  |  | $\mathrm{V}_{\mathrm{DD}}=4.5 \mathrm{~V}$ |  |  | 0.8 |  |
|  |  | $\mathrm{V}_{\mathrm{DD}}=3.6 \mathrm{~V}$ |  |  | 0.7 |  |
|  |  | $V_{D D}=3.0 \mathrm{~V}$ |  |  | 0.7 |  |
| Input Logic-High Voltage | $\mathrm{V}_{\mathrm{IH}}$ | $\mathrm{V}_{\mathrm{DD}}=5.5 \mathrm{~V}$ | 2.1 |  |  | V |
|  |  | $V_{D D}=4.5 \mathrm{~V}$ | 2.0 |  |  |  |
|  |  | $\mathrm{V}_{\mathrm{DD}}=3.6 \mathrm{~V}$ | 1.9 |  |  |  |
|  |  | $\mathrm{V}_{\mathrm{DD}}=3.0 \mathrm{~V}$ | 1.7 |  |  |  |
| AC CHARACTERISTICS |  |  |  |  |  |  |
| Power-Up Time | tPOR |  |  | 404 |  | ms |
| Enable Turn-On Time | ton | Figure 3, $\mathrm{V}_{\mathrm{IN}}= \pm 10 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega$, $C_{L}=15 \mathrm{pF}$ |  |  | 2 | ms |
| Enable Turn-Off Time | toff | Figure 3, $\mathrm{V}_{\mathrm{IN}}= \pm 10 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega$, $C_{L}=15 \mathrm{pF}$ |  |  | 1.5 | ms |
| Break-Before-Make Interval | $t_{\text {BBM }}$ | Figure $4, \mathrm{~V}_{\mathrm{IN}}= \pm 10 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega$, $C_{L}=15 \mathrm{pF}$ |  | 840 |  | $\mu \mathrm{s}$ |
| Charge Injection | Q | Figure 5, $\mathrm{V}_{\mathrm{A}_{-}}=0 \mathrm{~V}, \mathrm{C}_{\mathrm{L}}=1 \mathrm{nF}$ |  | 1720 |  | pC |
| Off-Isolation | $\mathrm{V}_{\text {ISO }}$ | $\begin{aligned} & \text { Figure } 6, \mathrm{~V}_{\mathrm{A}_{-}}=1 \mathrm{~V}_{\mathrm{RMS}}, \mathrm{f}=100 \mathrm{kHz}, \\ & R_{\mathrm{L}}=50 \Omega, \mathrm{C}_{\mathrm{L}}=15 \mathrm{pF} \end{aligned}$ |  | -80 |  | dB |
| Crosstalk | $\mathrm{V}_{\mathrm{CT}}$ | Figure 6, $\mathrm{f}=100 \mathrm{kHz}, \mathrm{R}_{S}=\mathrm{R}_{\mathrm{L}}=50 \Omega$ |  | -103 |  | dB |
| -3dB Bandwidth | BW | Figure 6, $\mathrm{R}_{S}=50 \Omega, \mathrm{R}_{\mathrm{L}}=50 \Omega$ |  | 75 |  | MHz |
| Total Harmonic Distortion Plus Noise | THD+N | $R_{S}=R_{L}=1 \mathrm{k} \Omega, \mathrm{f}=20 \mathrm{~Hz}$ to 20 kHz |  | 0.003 |  | \% |
| Input Capacitance | $\mathrm{C}_{\text {IN }}$ | A_, B_ pins |  | 78 |  | pF |
| THERMAL PROTECTION |  |  |  |  |  |  |
| Thermal-Shutdown Threshold | TSHUT |  |  | 145 |  | ${ }^{\circ} \mathrm{C}$ |
| Thermal-Shutdown Hysteresis | THYST |  |  | 25 |  | ${ }^{\circ} \mathrm{C}$ |
| ESD PROTECTION |  |  |  |  |  |  |
| A_, B_Pins (Note 4) |  | Human Body Model |  | $\pm 6$ |  | kV |
| All Other Pins |  | Human Body Model |  | $\pm 2$ |  | kV |

Note 2: All units are production tested at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$. Specifications over temperature are guaranteed by design.
Note 3: When $V_{D D}$ is higher than the charge-pump threshold, the internal 5 V regulated charge pump is turned off and the input to the high-voltage charge pumps is provided by $V_{D D}$.
Note 4: The MAX14778 requires a 100 nF capacitor on both $\mathrm{V}_{\mathrm{P}}$ and $\mathrm{V}_{\mathrm{N}}$ to $G N D$ to guarantee full ESD protection. See the Applications Information section for details on ESD test conditions.

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Test Circuits/Timing Diagrams


Figure 1. On-Resistance Measurement


Figure 2. Leakage Current Measurement

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 <br> <br> 4:1 Analog Multiplexer}

Test Circuits/Timing Diagrams (continued)


Figure 3. Turn-On/Turn-Off Timing


Figure 4. Break-Before-Make Timing

## Dual $\pm 25 \mathrm{~V}$ Above- and Below-the-Rails 4:1 Analog Multiplexer

Test Circuits/Timing Diagrams (continued)


Figure 5. Charge Injection


MEASUREMENTS ARE STANDARDIZED AGAINST SHORTS AT IC TERMINALS.
OFF-ISOLATION IS MEASURED BETWEEN ACOM AND "OFF" A TERMINAL ON EACH MULTIPLEXER.
-3dBW IS MEASURED BETWEEN ACOM AND "ON" A_ TERMINAL ON EACH MULTIPLEXER.
CROSSTALK IS MEASURED FROM ONE CHANNEL TO ALL OTHER CHANNELS.
SIGNAL DIRECTION THROUGH MULTIPLEXER IS REVERSED; WORST VALUES ARE RECORDED.

Figure 6. Off-Isolation, -3dB Bandwidth, and Crosstalk

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Typical Operating Characteristics
( $\mathrm{V}_{\mathrm{DD}}=5.0 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)


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## Dual $\mathbf{\pm 2 5 V}$ Above- and Below-the-Rails 4:1 Analog Multiplexer

Typical Operating Characteristics (continued)
$\left(\mathrm{V}_{\mathrm{DD}}=5.0 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}\right.$, unless otherwise noted. $)$
THD+N vs. FREQUENCY


TURN-ON TIME
vs. ANALOG-SIGNAL VOLTAGE


CHARGE PUMP NOISE WITH
SWITCH ENABLED


PSRR vs. FREQUENCY


TURN-OFF TIME
vs. ANALOG-SIGNAL VOLTAGE


CHARGE PUMP NOISE WITH SWITCH DISABLED


# Dual $\mathbf{\pm 2 5 V}$ Above- and Below-the-Rails 4:1 Analog Multiplexer 

Pin Configuration


Pin Description

| PIN | NAME |  |
| :---: | :---: | :--- |
| 1 | BCOM | MUX B Common Terminal |
| 2 | $V_{P}$ | Positive Charge-Pump Output. Bypass $V_{P}$ to GND with a 100nF 50V ceramic capacitor. |
| 3 | GND | Ground |
| 4 | $V_{N}$ | Negative Charge-Pump Output. Bypass $V_{N}$ to GND with a 100nF 50V ceramic capacitor. |
| 5 | ACOM | MUX A Common Terminal |
| 6 | A0 | MUX A Bidirectional Analog Input/Output 0 |
| 7 | A1 | MUX A Bidirectional Analog Input/Output 1 |
| 8 | A2 | MUX A Bidirectional Analog Input/Output 2 |
| 9 | A3 | MUX A Bidirectional Analog Input/Output 3 |
| 10 | ENA | MUX A Enable Input |
| 11 | SA0 | MUX A Channel Select Input 0 |
| 12 | SA1 | MUX A Channel Select Input 1 |
| 13 | V $_{\text {DD }}$ | Power-Supply Input. Bypass $V_{\text {DD }}$ to GND with a 1 $\mu \mathrm{F}$ ceramic capacitor. |
| 14 | SB1 | MUX B Channel Select Input 1 |
| 15 | SB0 | MUX B Channel Select Input 0 |
| 16 | ENB | MUX B Enable Input |
| 17 | B3 | MUX B Bidirectional Analog Input/Output 3 |
| 18 | B2 | MUX B Bidirectional Analog Input/Output 2 |
| 19 | B1 | MUX B Bidirectional Analog Input/Output 1 |
| 20 | B0 | MUX B Bidirectional Analog Input/Output 0 |
| - | EP | Exposed Pad. Connect EP to V/ VP is not intended as an electrical connection point. |

# Dual $\pm 25 V$ Above- and Below-the-Rails 4:1 Analog Multiplexer 

Truth Tables

## Table 1. MUX A Channel Selection

| ENA | SA1 | SAO | ACOM <br> CONNECTED TO |
| :---: | :---: | :---: | :---: |
| 0 | $X$ | $X$ | Open |
| 1 | 0 | 0 | A0 |
| 1 | 0 | 1 | A1 |
| 1 | 1 | 0 | A2 |
| 1 | 1 | 1 | A3 |

$X=$ Don't care

## Detailed Description

The MAX14778 dual 4:1 analog multiplexer integrates bias circuitry to provide a $\pm 25 \mathrm{~V}$ analog voltage range with a single 3.0 to 5.5 V supply. This extended input range allows multiplexing different communications signals such as RS-232, RS-485, audio and USB 1.1 onto the same connector.

## Integrated Bias Generation

The MAX14778 contains a total of three charge pumps to generate bias voltages for the internal switches: a 5 V regulated charge pump, a positive high-voltage ( +35 V ) charge pump, and a negative high-voltage (-27V) charge pump. When $\mathrm{V}_{\mathrm{DD}}$ is above 4.7 V (typ), the 5 V regulated charge pump is bypassed and $V_{D D}$ provides the input for the highvoltage charge pumps, reducing overall supply current.
An external 100nF capacitor is required for each highvoltage charge pump between $\mathrm{V}_{\mathrm{P}} / \mathrm{V}_{\mathrm{N}}$ and GND.

## Analog Signal Levels

The MAX14778 transmits signals of up to $\pm 25 \mathrm{~V}$ with a single 3.0 to 5.5 V supply due to integrated bias circuitry. The device features $1.5 \Omega$ (max) on-resistance and $3 \mathrm{~m} \Omega$ (typ) flatness for analog signals between -25 V and +25 V (see the Typical Operating Characteristics). The current flow through the multiplexers can be bidirectional, allowing operation either as a multiplexer or demultiplexer.

Table 2. MUX B Channel Selection

| ENB | SB1 | SB0 | BCOM <br> CONNECTED TO |
| :---: | :---: | :---: | :---: |
| 0 | $X$ | $X$ | Open |
| 1 | 0 | 0 | B0 |
| 1 | 0 | 1 | B1 |
| 1 | 1 | 0 | B2 |
| 1 | 1 | 1 | B3 |

$X=$ Don't care

Digital Interface
The MAX14778 has two digital select inputs for each MUX: SA1 and SA0 control MUX A; SB1 and SB0 control MUX B. Drive the digital select inputs high or low to select which input ( $A_{-}, B_{-}$) is connected to the common terminal (ACOM, BCOM) for each MUX. See the Truth Tables for more information.
Each MUX features an independent enable input (ENA and ENB). Drive ENA or ENB low to disconnect all inputs from the common terminal for that MUX, regardless of the status of the select inputs or the other enable input.

## Applications Information

## Connector Sharing

The MAX14778 supports a $\pm 25 \mathrm{~V}$ analog signal range independently for each input/output, allowing physical connector sharing between interface types that have differing signal ranges.
The multiprotocol connector-sharing application in the Typical Operating Circuits shows an application with RS-232, half-duplex RS-485, full-speed USB 1.1, and audio signals sharing the same connector. The device allows signals to pass over the entire signal range specified by each standard while safely isolating the unused transceivers.

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Non-Powered Condition
The MAX14778 can tolerate input voltages on the A_, B_, ACOM, and BCOM pins in the $\pm 25 \mathrm{~V}$ range when it is not powered.
When VDD $=0 \mathrm{~V}$, the DC input leakage current into the $A_{-}, B_{-}, A C O M$ or $B C O M$ pins will typically be below $1 \mu \mathrm{~A}$. Some devices can have a larger leakage current up to mA range due to technology spread.
With VDD not powered, internal diodes between the analog pins and the VP and VN will charge up the external capacitors on VP and VN when positive and/or negative voltages are applied to these pins. This causes transient input current flow.
Large dv/dt on the inputs causes large capacitive charging currents, which have to be limited to the 300 mA Absolute Maximum Ratings in order to not destroy the internal diodes. With 100 nF capacitors on VP and VN, the dv/dt must be limited to $3 \mathrm{~V} / \mu \mathrm{s}$ once the capacitors reach their final voltage; the input current decays to the leakage current levels mentioned above.


Figure 7. Human Body ESD Test Model

High-ESD Protection
Electrostatic discharge (ESD)-protection structures are incorporated on all pins to protect against electrostatic discharges up to $\pm 2 \mathrm{kV}$ Human Body Model (HBM) encountered during handling and assembly. $A_{-}$and $B_{-}$ are further protected against ESD up to $\pm 6 \mathrm{kV}$ (HBM) without damage. The ESD structures withstand high ESD both in normal operation and when the device is powered down. After an ESD event, the MAX14778 continues to function without latchup.

ESD Test Conditions
ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test setup, test methodology, and test results.
The MAX14778 requires a 100nF capacitor on both $V_{p}$ and $V_{N}$ to GND to guarantee full ESD protection.

Human Body Model
Figure 7 shows the Human Body Model. Figure 8 shows the current waveform it generates when discharged into a low impedance. This model consists of a 100 pF capacitor charged to the ESD voltage of interest that is then discharged into the device through a $1.5 \mathrm{k} \Omega$ resistor.


Figure 8. Human Body Current Waveform

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Typical Operating Circuits


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Typical Operating Circuits (continued)


## Dual $\pm 25 \mathrm{~V}$ Above- and Below-the-Rails 4:1 Analog Multiplexer

## Ordering Information

| PART | TEMP RANGE | PIN-PACKAGE |
| :---: | :---: | :---: |
| MAX14778ETP + | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 20 TQFN-EP* |

+Denotes a lead(Pb)-free/RoHS-compliant package.
*EP = Exposed pad.
Chip Information
PROCESS: BiCMOS

## Package Information

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "\#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

| PACKAGE <br> TYPE | PACKAGE <br> CODE | OUTLINE <br> NO. | LAND <br> PATTERN NO. |
| :---: | :---: | :---: | :---: |
| 20 TQFN-EP | T2055+4 | $\underline{21-0140}$ | $\underline{90-0009}$ |

# Dual $\pm 25 \mathrm{~V}$ Above- and Below-the-Rails 4:1 Analog Multiplexer 

Revision History

| REVISION <br> NUMBER | REVISION <br> DATE | DESCRIPTION | PAGES <br> CHANGED |
| :---: | :---: | :--- | :---: |
| 0 | $6 / 11$ | Initial release | - |
| 1 | $6 / 12$ | Added new TOCs 14 and 15, updated Non-Powered Condition section, updated <br> Note 4, Pin Description, ESD Test Conditions, Typical Operating Circuits, updated <br> capacitor values | $3,8,9,10,11$, <br> 12,13 |

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